

# Claims

- [c1]      What is claimed is:
1. A wafer holder for semiconductor manufacturing devices, the wafer holder having a wafer-carrying surface and comprising:  
a shaft joined to the wafer holder for supporting the wafer holder;  
an electrical circuit formed either on a surface other than the wafer-carrying surface of the wafer holder, or else inside it; and  
electrodes within said shaft, for supplying power to said electrical circuit, the heat capacity of said electrodes where they are within said shaft being 10% or less of the heat capacity of a region of the wafer holder that corresponds to inside the outer periphery of said shaft.
  - [c2]      2. The wafer holder set forth in claim 1, wherein the electrical circuit formed in the wafer holder is at least a resistive heating element.
  - [c3]      3. A semiconductor manufacturing device wherein the wafer holder set forth in claim 1 is installed.
  - [c4]      4. A semiconductor manufacturing device wherein the wafer holder set forth in claim 2 is installed.